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## Change of IC/LSI package outline

**1960s** Era of non-fixed lead assembly  
 Age of TOP  
 TOP: Transistor Outline Package

**1970s** Era of pin insertion assembly  
 Age of DIP  
 DIP: Dual In-line Package

**1980s** Era of Surface mount assembly  
 Age of QFP  
 QFP: Quad Flat Package

**1990s** Era of small outline surface assembly  
 Age of CSP  
 CSP: Chip Scale Package

**2000s** Era of 3D stacked assembly  
 Age of SiP  
 SiP: System in Package

**Era of system assembly after 2010**  
 Age of MiP  
 MiP: Multi functions in a Package

